

METHODS FOR PACKAGING MICROELECTRONIC DEVICES AND
MICROELECTRONIC DEVICES
FORMED USING SUCH METHODS

ABSTRACT OF THE DISCLOSURE

Methods for packaging microelectronic devices and microelectronic devices formed using such methods are disclosed herein. One aspect of the invention is directed toward a method for packaging a microelectronic device that includes coupling an active side of a microelectronic die to a surface of a support member. The microelectronic die can have a backside opposite the active side, a peripheral side extending at least part way between the active side and the backside, and at least one through-wafer interconnect. The method can further include applying an encapsulant to cover a portion of the surface of the support member so that a portion of the encapsulant is laterally adjacent to the peripheral side, removing material from a backside of the microelectronic die to expose a portion of at least one through-wafer interconnect, and applying a redistribution structure to the backside of the microelectronic die.

Figure : 1